BGA Heat Sink - High Performance

Device Specific - NXP





*Image above is for illustration purpose only.

ATS Part#: ATS-59006-C1-R0

29.00 x 37.00 x 11.00 mm BGA Heat Sink - High Performance Device Specific - NXP Description:

Heat Sink Type: NXP Heat Sink Attachment: maxiGRIP

Equivalent Part Number: ATS-59006-C2-R0 Discontinued

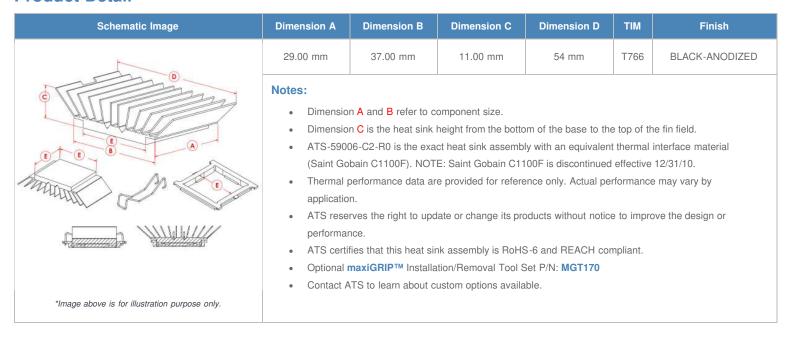
Features & Benefits

- Designed for flip-chip processors such as NXP MPCs
- maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- Comes preassembled with high performance, phase changing, thermal interface material

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	6.2 °C/W	4.9 °C/W	4.2 °C/W	3.7 °C/W	3.3 °C/W	3 °C/W	2.8 °C/W
	Ducted Flow	3.8	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail



For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.

